



Test Report issued under the responsibility of:



TEST REPORT
IEC 60269-4
Low-voltage fuses
Part 4: Supplementary requirements for fuse-links for the protection of semiconductor devices

Report Number: 03601-A-24CB0182-S
Date of issue: 2024-12-10
Total number of pages: 28



Name of Testing Laboratory preparing the Report.....: Suzhou Electrical Apparatus Science Research Institute Co., Ltd.(EETI)

Applicant's name.....: Zhejiang Tengen Electric Co., Ltd.

Address: Sulv Industry Zone, Liushi Town, Yueqing City, Zhejiang Province, P.R.China.

Test specification:

Standard: IEC 60269-4:2009, IEC 60269-4:2009/AMD1:2012, IEC 60269-4:2009/AMD2:2016
see also IEC 60269-1:2006, IEC 60269-1:2006/AMD1:2009, IEC 60269-1:2006/AMD2:2014

Test procedure: CB Scheme

Non-standard test method: N/A

TRF template used: IECEE OD-2020-F1:2022, Ed.1.5

Test Report Form No.: IEC60269_4D

Test Report Form(s) Originator: CQC

Master TRF: Dated 2023-08-17

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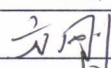
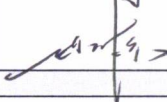
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Test item description	Fuse for protection of semiconductor devices	
Trade Mark	Tengen	
Manufacturer	Zhejiang Tengen Electric Co., Ltd. Sulv Industry Zone, Liushi Town, Yueqing City, Zhejiang Province, P.R.China.	
Model/Type reference	TGRS3Z-200BQ, TGRS3Z-200CQ	
Ratings	Un:DC250V/DC500V/DC750V/AC500V/AC690V/AC800V; In:10A,16A,20A,25A,32A,40A,50A,63A,80A,100A,125A,160A,180A,200A; I1:50kA(DC250V/DC500V/DC750V);100kA(AC500V/AC690V/AC800V);aR.	
Responsible Testing Laboratory (as applicable), testing procedure and testing location(s):		
<input checked="" type="checkbox"/>	CB Testing Laboratory:	Suzhou Electrical Apparatus Science Research Institute Co., Ltd.(EETI)
Testing location/ address		No.7 Yonghe Street, Binhe Road, New District, Suzhou, China
Tested by (name, function, signature).		Fang Gang(Team leader) 
Approved by (name, function, signature)		Chen Yuan (Supervisor) 
<input type="checkbox"/>	Testing procedure: CTF Stage 1:	
Testing location/ address		
Tested by (name, function, signature).		
Approved by (name, function, signature)		
<input type="checkbox"/>	Testing procedure: CTF Stage 2:	
Testing location/ address		
Tested by (name + signature).....		
Witnessed by (name, function, signature)		
Approved by (name, function, signature)		
<input type="checkbox"/>	Testing procedure: CTF Stage 3:	
<input type="checkbox"/>	Testing procedure: CTF Stage 4:	
Testing location/ address		
Tested by (name, function, signature).		
Witnessed by (name, function, signature)		
Approved by (name, function, signature)		
Supervised by (name, function, signature)		